

CLAIMS:

5 What is claimed is:

1. A coil bobbin comprising:

10 a housing having a floor with at least one electrical lead-in projecting therethrough
for attachment to a printed circuit board, said at least one electrical lead-in being provided
with thermal-strain relief between said floor and said printed circuit board.

2. The coil bobbin of Claim 1 wherein said thermal-strain relief comprises at least one
loop formed in said electrical lead-in.

15 3. The coil bobbin of Claim 2 wherein said loop comprises a U-shaped portion.

4. The coil bobbin of Claim 2 wherein said loop comprises an O-shaped portion.